

System Lens Drivers

μ -step System Lens Driver for Digital Still Cameras


BU24035GW
General Description

BU24035GW is a system Lens Driver that uses μ -step driving to make the configuration of the sophisticated, high precision and low noise lens driver system possible. This IC has a built-in driver for both DC motor and voice coil motor and a μ -step controller that decreases CPU power. Therefore, multifunctional lens can be applied.

Features

- Built-in 6 channels Driver block
 - 1ch-4ch: Voltage control type H-bridge (Adaptable to STM 2systems)
 - 5ch: Voltage / Current control type H-bridge
 - 6ch: Current control type H-bridge
- Built-in 2 channels PI driving circuit
- Built-in 1 channels Waveforming circuit
- Built-in FLL digital servo circuit
- Built-in PLL circuit
- Built-in STM control circuit : Autonomous control (cache / updown mode), Clock IN control

Key Specifications

- Digital Power Supply Voltage: 2.7V to 3.6V
- Driver Power Supply Voltage: 2.7V to 5.5V
- Output Current (1ch-4ch,6ch): $\pm 500\text{mA}(\text{Max})$
- Output Current (5ch): $\pm 600\text{mA}(\text{Max})$
- Input Clock Frequency: 1MHz to 28MHz
- FET ON Resistance (1ch-4ch): $1.5\Omega(\text{Typ})$
- FET ON Resistance (5ch,6ch): $1.0\Omega(\text{Typ})$
- Operating Temperature Range: -20°C to $+85^{\circ}\text{C}$

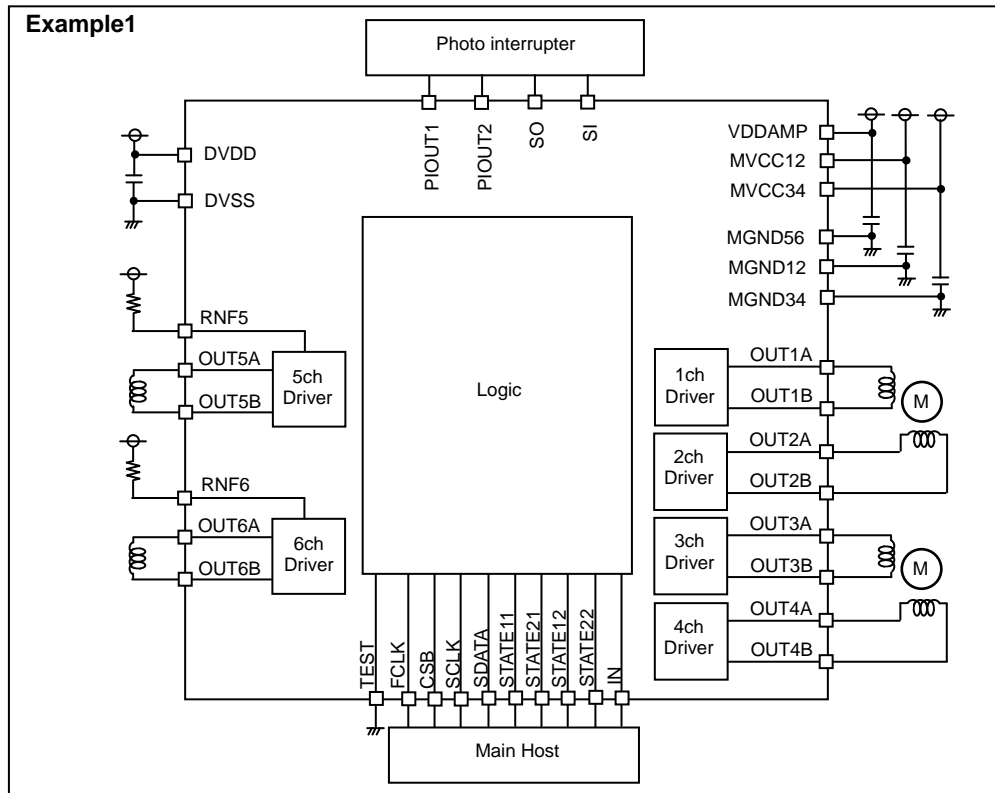
Package

UCSP75M3

3.10mm x 3.10mm x 0.850mm

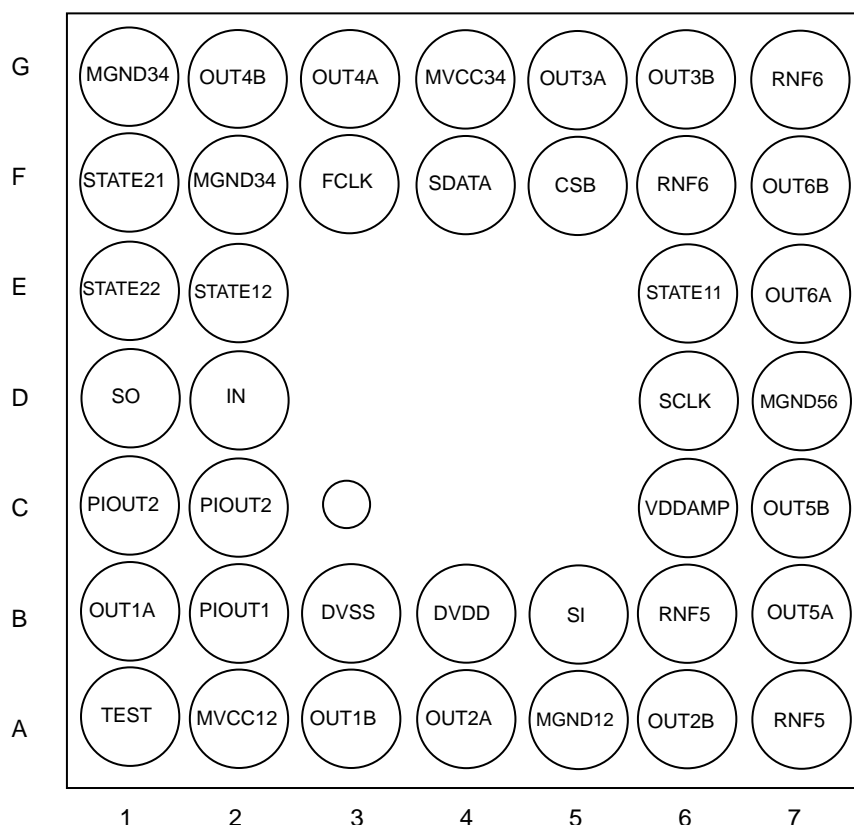
Applications

- Digital still cameras

Typical Application Circuit


●Pin Configuration

(Bottom view)



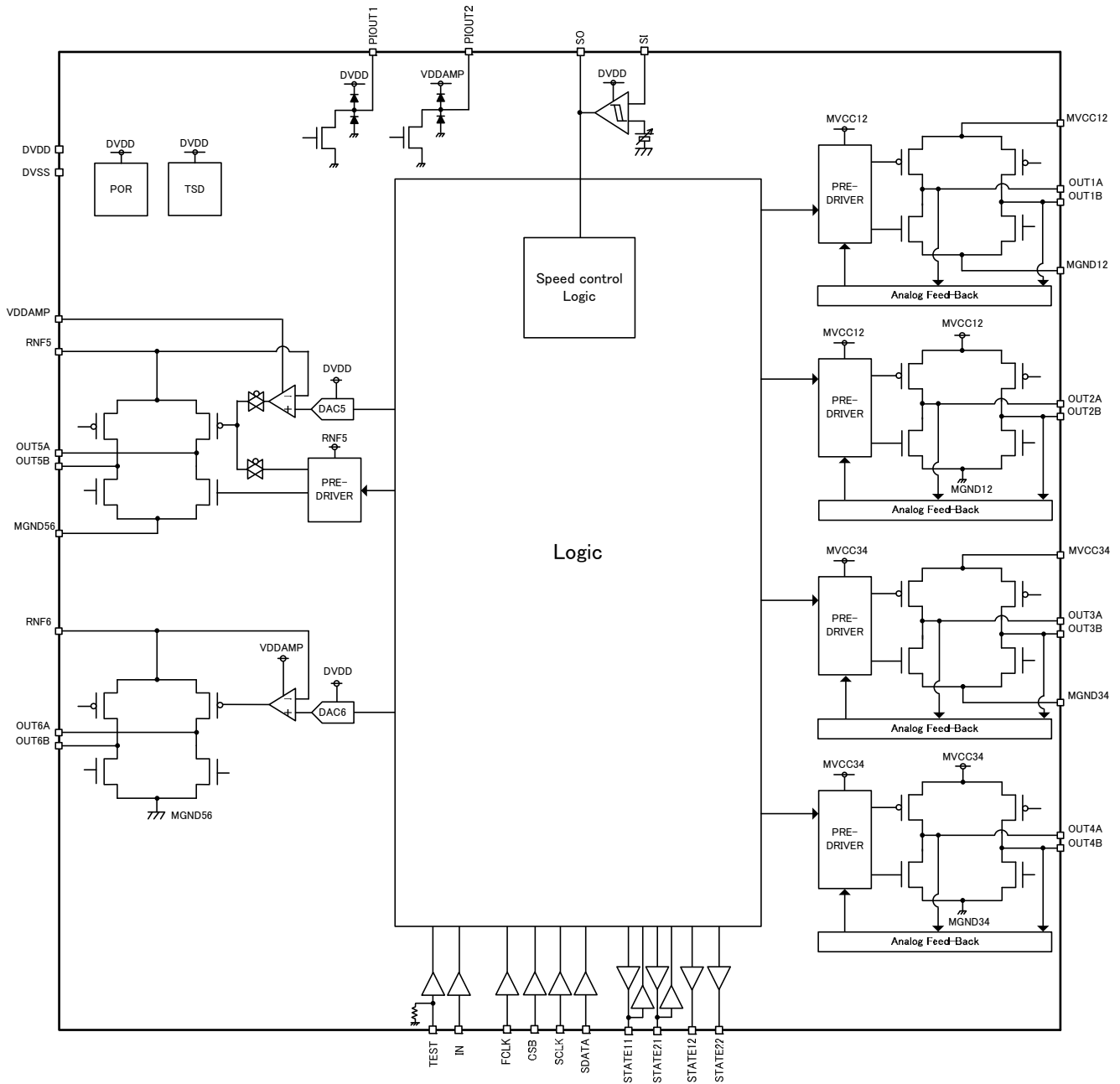
●Pin Description

| Land Matrix No. | Pin Name | Power Supply | Function | Land Matrix No. | Pin Name | Power Supply | Function |
|-----------------|----------|--------------|------------------------------|-----------------|----------|--------------|---|
| B4 | DVDD | - | Digital power supply | B1 | OUT1A | MVCC12 | 1ch Driver A output |
| B3 | DVSS | - | ground | A3 | OUT1B | MVCC12 | 1ch Driver B output |
| F3 | FCLK | DVDD | FCLK logic input | A4 | OUT2A | MVCC12 | 2ch Driver A output |
| F5 | CSB | DVDD | CSB logic input | A6 | OUT2B | MVCC12 | 2ch Driver B output |
| D6 | SCLK | DVDD | SCLK logic input | G4 | MVCC34 | - | 3ch, 4ch Driver power supply |
| F4 | SDATA | DVDD | SDATA logic input | G1,F2(*) | MGND34 | - | 3ch, 4ch Driver ground |
| D2 | IN | DVDD | IN logic input | G5 | OUT3A | MVCC34 | 3ch Driver A output |
| E6 | STATE11 | DVDD | STATE11 logic input/output | G6 | OUT3B | MVCC34 | 3ch Driver B output |
| F1 | STATE21 | DVDD | STATE21 logic input/output | G3 | OUT4A | MVCC34 | 4ch Driver A output |
| E2 | STATE12 | DVDD | STATE12 logic output | G2 | OUT4B | MVCC34 | 4ch Driver B output |
| E1 | STATE22 | DVDD | STATE22 logic output | C6 | VDDAMP | - | 5ch, 6ch Power supply of current driver control |
| A1 | TEST | DVDD | TEST logic input | D7 | MGND56 | - | 5ch,6ch Driver ground |
| B2 | PIOUT1 | DVDD | PI driving output 1 | A7,B6(*) | RNF5 | - | 5ch Driver power supply |
| C1,C2 | PIOUT2 | VDDAMP | PI driving output 2 | B7 | OUT5A | RNF5 | 5ch Driver A output |
| B5 | SI | DVDD | Waveforming input | C7 | OUT5B | RNF5 | 5ch Driver B output |
| D1 | SO | DVDD | Waveforming output | F6,G7(*) | RNF6 | - | 6ch Driver power supply |
| A2 | MVCC12 | - | 1ch, 2ch Driver power supply | E7 | OUT6A | RNF6 | 6ch Driver A output |
| A5 | MGND12 | - | 1ch, 2ch Driver ground | F7 | OUT6B | RNF6 | 6ch Driver B output |

(*) It is not possible to use corner pin only.(Corner pins are A7, G1, and G7.)

Please short A7-B6, F2-G1, F6-G7 and use it at the same time

●Block Diagram



●Description of Blocks

Stepping Motor Driver (1ch-4ch Driver)

Built-in stepping motor driver of PWM driving type.

Maximum 2 stepping motor can be driven independently.

Built-in voltage feedback circuit of D-class type.

3ch/4ch drivers can also drive independently for DC motor or voice coil motor.

(1) Control

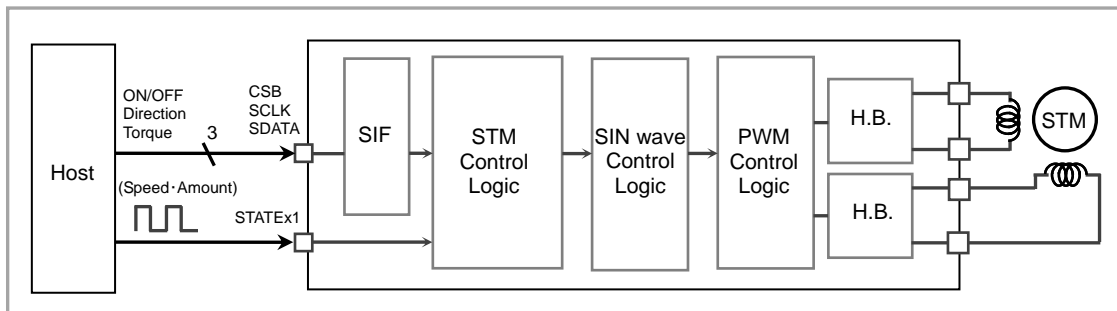
It corresponds to both Clock IN and Autonomous control.

(i)Clock IN Control

Set the registers for the stepping motor control.

The stepping motor is rotated and synchronized with the input clock in the STATE pin.

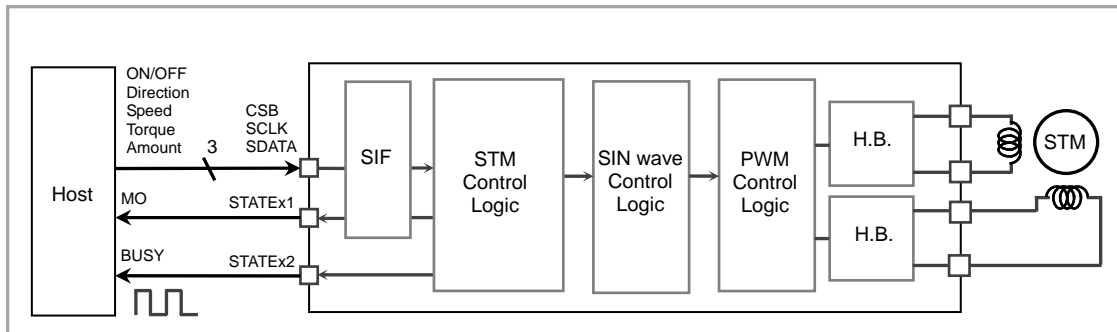
It is possible to select the mode of stepping motor control from μ -step, 1-2 phase excitation, 2 phase excitation and the number of edge for electrical angle cycle from 4, 8, 32, 64, 128, 256, 512 or 1024.



(ii)Autonomous Control

The stepping motor is rotated by setting the registers for the stepping motor control.

It is possible to select the mode of stepping motor control from μ -step (1024 portion), 1-2 phase excitation and 2 phase excitation.



Cache Method

Built-in Cache registers.

Cache registers enable the setting of subsequent process while the motor is in operation. Through these registers, operations are done continuously.

Up down method

It is possible to set Up, Constant and Down operation before the motor is operates.

●Description of Blocks

Voltage / Current Driver (5ch Driver)

Built-in voltage driver of PWM driving type / constant current driver.

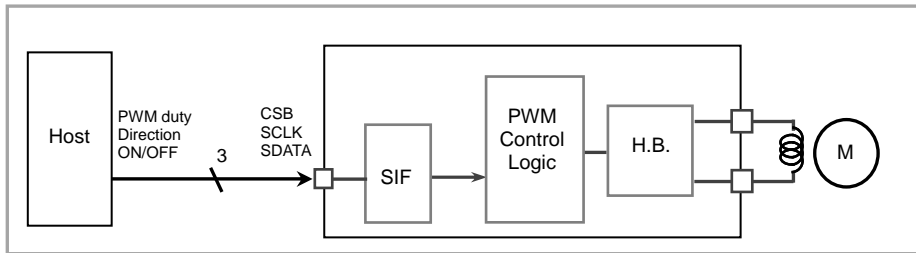
Built-in digital FLL speed control logic for voltage driver.

(1) Control

(i) Register Control

■ Voltage Driver (at speed control = OFF)

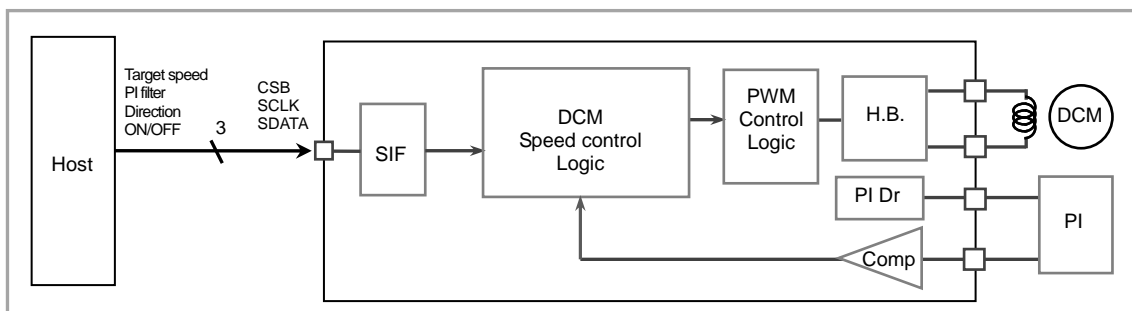
The PWM drive is executed by the PWM duty ratio, the PWM direction and the PWM ON/OFF which are controlled by the register settings.



■ Voltage Driver (at speed control = ON)

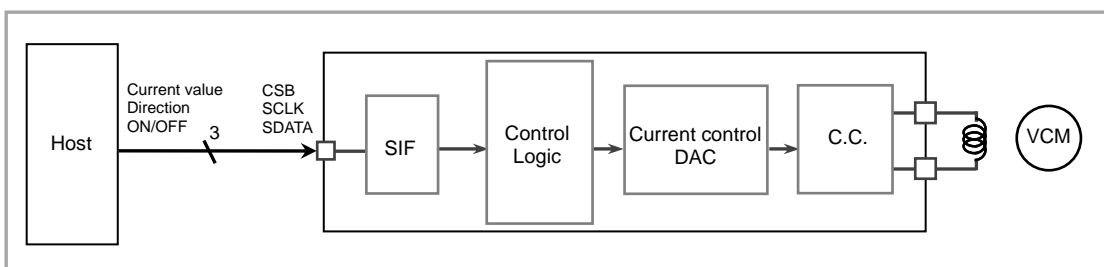
The speed control drive is executed by the target speed value, the direction, the coefficient value of PI filter and the turning ON/OFF which are controlled by the register settings.

The motor speed is adjusted by comparing the target speed with the motor speed detected at the signal of photo-interrupter.



■ Current Driver

The constant current drive is executed by the output current value, the current direction and the current ON/OFF which are controlled by the register settings.

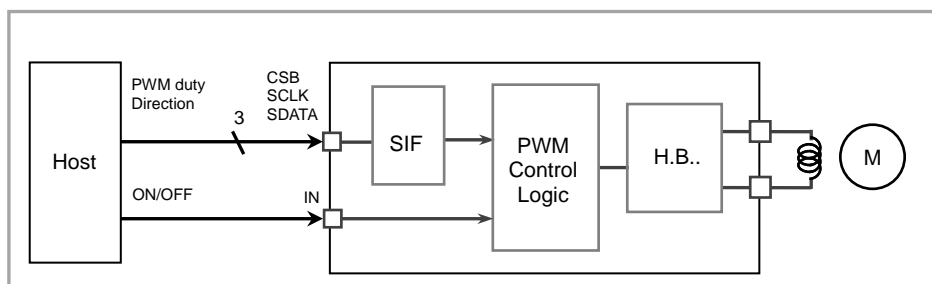


●Description of Blocks

(ii)External Pin Control

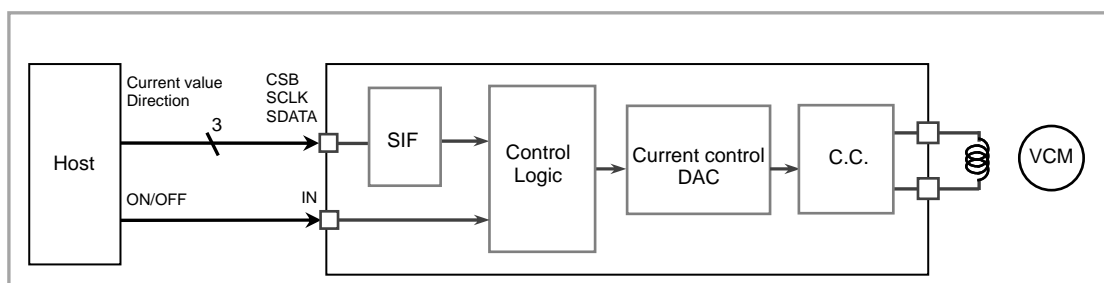
■Voltage Driver (only at speed control = OFF)

The PWM drive is executed by the PWM duty ratio and the PWM direction which are controlled by the register settings. The PWM ON/OFF is controlled by IN pin.



■Current Driver

The constant current drive is executed by the output current value and current direction which are controlled by the register settings. Constant current driving ON/OFF is controlled by IN pin.



●Description of Blocks

Current Driver (6ch Driver)

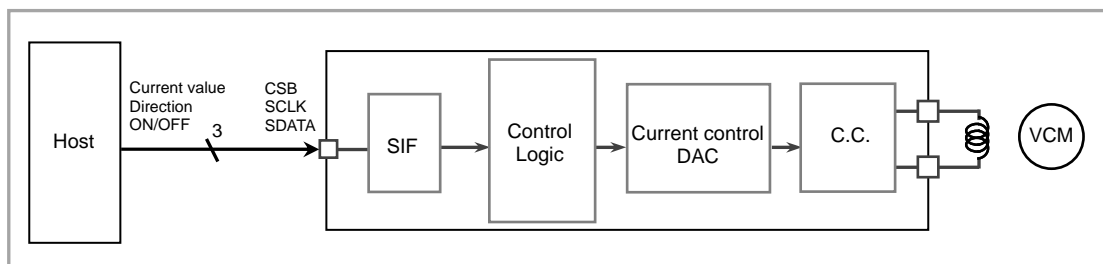
Built-in constant current driver.

The voltage of RNF pin and the external resistor (RRNF) determine the amount of output current. The internal high-precision amplifier (CMOS gate input) is used for on the constant current control. If any resistance component exists in the wirings of RNF pin and the external resistor (RRNF), the precision can be reduced. To avoid this, pay utmost attention to the wirings.

(1) Control

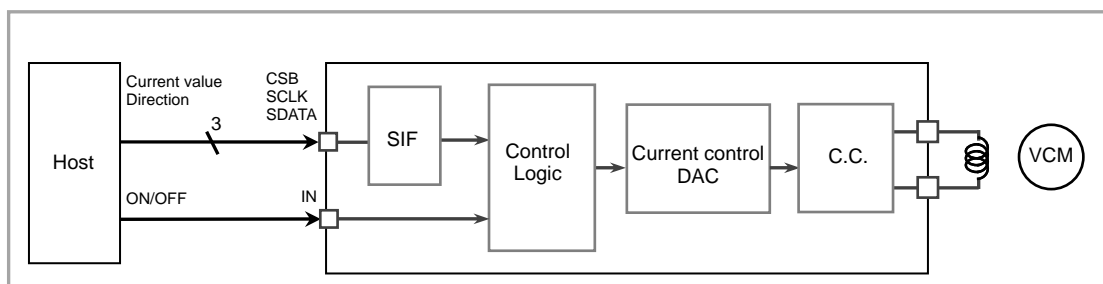
(i)Register Control

The constant current drive is executed by the output current value, the current direction and the current ON/OFF which are controlled by the register settings.



(ii)External Pin Control

The constant current drive is executed by the output current value and current direction which are controlled by the register settings. Constant current driving ON/OFF is controlled by IN pin.



●Absolute Maximum Ratings (Ta=25°C)

| Parameter | Symbol | Limit | Unit | Remark |
|-----------------------------|--------|----------------------------|------|------------------------|
| Power Supply Voltage | DVDD | -0.3 to +4.5 | V | |
| | MVCC | -0.3 to +7.0 | V | MVCC12, MVCC34, VDDAMP |
| Input Voltage | VIN | -0.3 to supply voltage+0.3 | V | |
| Input / Output Current *1 | IIN | ±500 | mA | MVCC12, MVCC34, RNF6 |
| | | ±600 | mA | RNF5 |
| | | +50 | mA | PIOUT1 |
| | | +150 | mA | PIOUT2 |
| Storage Temperature Range | TSTG | -55 to +125 | °C | |
| Operating Temperature Range | TOPE | -20 to +85 | °C | |
| Permissible Dissipation *2 | PD | 1050 | mW | |

*1 Must not exceed PD.

*2 To use at a temperature higher than Ta=25 °C, derate 10.5mW per 1 °C
(At mounting 50mm x 58mm x 1.75mm glass epoxy board.)

●Recommended Operating Rating (Ta=25°C)

| Parameter | Symbol | Limit | Unit | Remark |
|------------------------------|--------|------------|------|------------------------------------|
| Digital Power Supply Voltage | DVDD | 2.7 to 3.6 | V | $DVDD \leq MVCC$ |
| Driver Power Supply Voltage | MVCC | 2.7 to 5.5 | V | MVCC12, MVCC34, RNF5, RNF6, VDDAMP |
| Clock Operating Frequency | FCLK | 1 to 28 | MHz | Reference clock |

●Electrical Characteristics

(Unless otherwise specified, Ta=25°C, DVDD=3.0V, MVCC=5.0V, DVSS=MGND=0.0V)

| Parameter | Symbol | Limit | | | Unit | Conditions |
|--|--------|---------|------|---------|----------|--|
| | | MIN | TYP | MAX | | |
| <Current Consumption> | | | | | | |
| Quiescence (DVDD) | ISSD | - | 20 | 50 | μ A | CMD_RS=0 |
| (MVCC) | ISSM | - | 0 | 10 | μ A | |
| Operation (DVDD) | IDDD | - | 6 | 10 | mA | CMD_RS=STB=CLK_EN=1 FCLK=24MHz CLK_DIV setting : 0h No load |
| <Logic Block> | | | | | | |
| Low-level Input Voltage | VIL | DVSS | - | 0.3DVDD | V | |
| High-level Input Voltage | VIH | 0.7DVDD | - | DVDD | V | |
| Low-level Input Current | IIL | 0 | - | 10 | μ A | VIL=DVSS |
| High-level Input Current | IIH | 0 | - | 10 | μ A | VIH=DVDD |
| Low-level Output Voltage | VOL | DVSS | - | 0.2DVDD | V | IOL=1.0mA |
| High-level Output Voltage | VOH | 0.8DVDD | - | DVDD | V | IOH=1.0mA |
| <PI Driving Circuit> | | | | | | |
| Output Voltage | PIVO | - | 0.15 | 0.5 | V | IIH=30mA |
| <Waveforming Circuit> | | | | | | |
| Detective Voltage Error | Vth | 1.4 | 1.5 | 1.6 | V | Vth setting : 20h |
| <Voltage Driver Block 1ch-4ch> | | | | | | |
| ON-resistance | Ron | - | 1.5 | 2.0 | Ω | IO=±100mA (the sum of high and low sides) |
| OFF-leak Current | IOZ | -10 | 0 | +10 | μ A | Output Hiz setting |
| Average Voltage Accuracy between different Output Pins | Vdiff | -5 | - | +5 | % | Vdiff setting : 2Bh |
| <Voltage / Current Driver Block 5ch> | | | | | | |
| ON-resistance | Ron | - | 1.0 | 1.5 | Ω | IO=±100mA (the sum of high and low sides) |
| OFF-leak Current | IOZ | -10 | 0 | +10 | μ A | Output Hiz setting |
| Output Current | IO | 190 | 200 | 210 | mA | At the current driver mode DAC setting : 82h RRNF=1 Ω |
| <Current Driver Block 6ch> | | | | | | |
| ON-resistance | Ron | - | 1.0 | 1.5 | Ω | IO=±100mA (the sum of high and low sides) |
| OFF-leak Current | IOZ | -10 | 0 | +10 | μ A | Output Hiz setting |
| Output Current | IO | 190 | 200 | 210 | mA | DAC setting : 80h RRNF=1 Ω |

●Typical Performance Curves

(Unless otherwise specified, Ta=25°C, DVDD=3.0V, MVCC=5.0V, DVSS=MGND=0.0V)

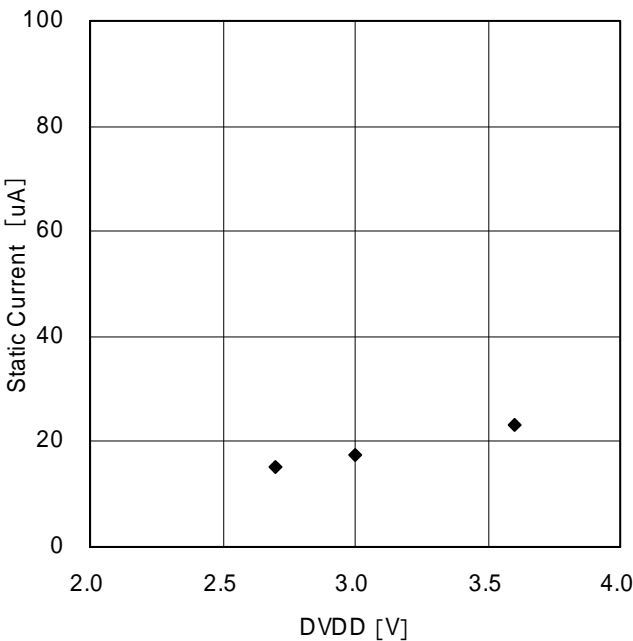


Figure 1. DVDD Static Current
Voltage Dependency

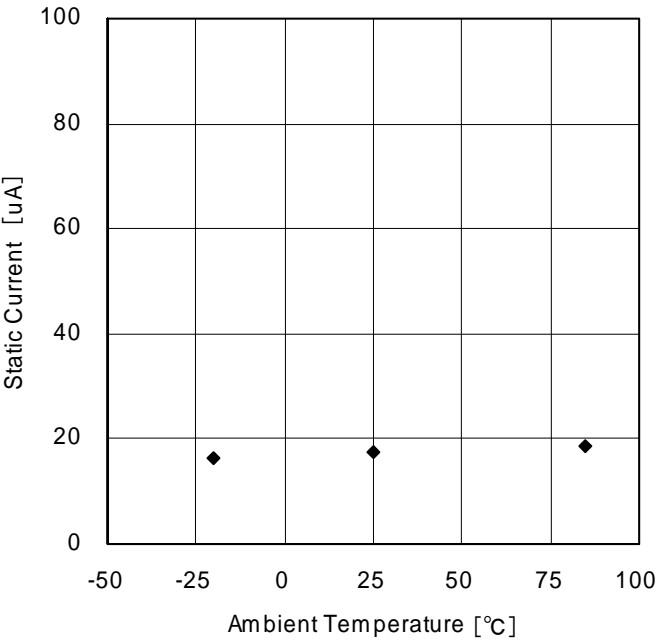


Figure 2. DVDD Static Current
Temperature Dependency

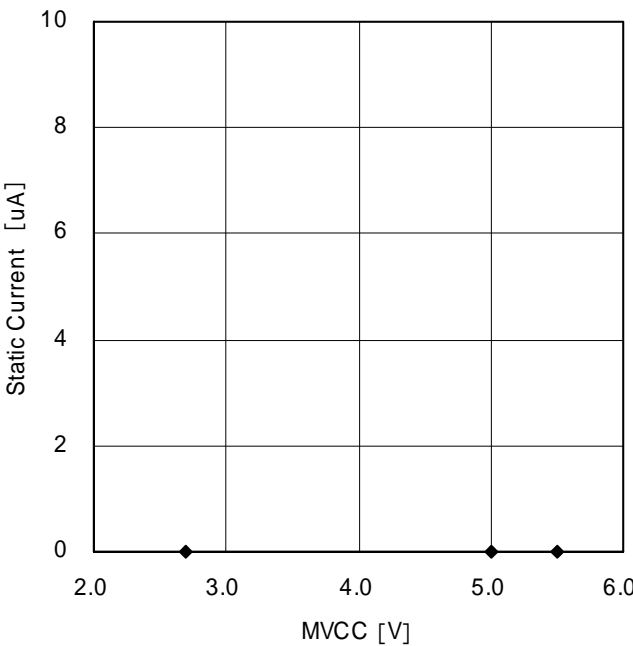


Figure 3. MVCC Static Current
Voltage Dependency

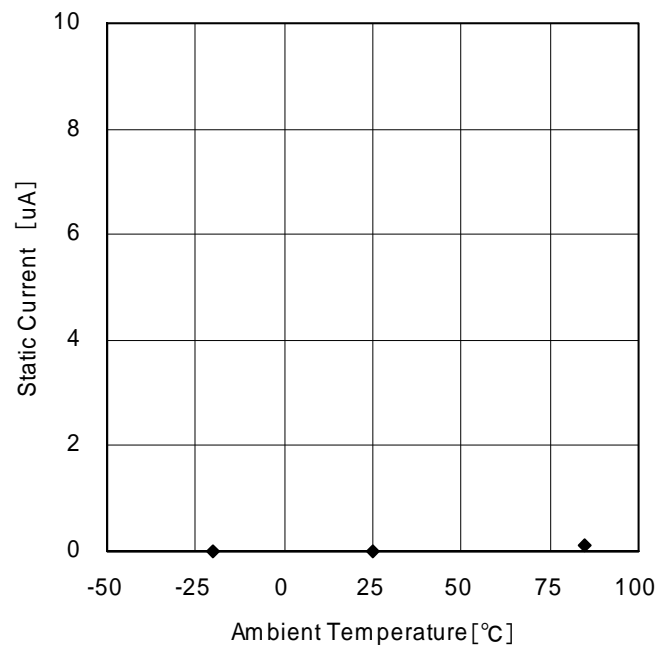


Figure 4. MVCC Static Current
Temperature Dependency

●Typical Performance Curves

(Unless otherwise specified, Ta=25°C, DVDD=3.0V, MVCC=5.0V, DVSS=MGND=0.0V)

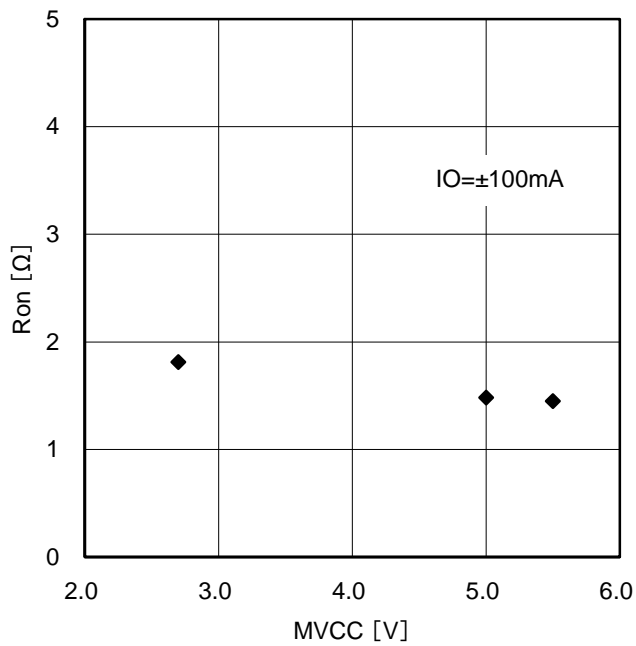


Figure 5. Output ON-Resistance
MVCC Dependency
(Voltage driver block)

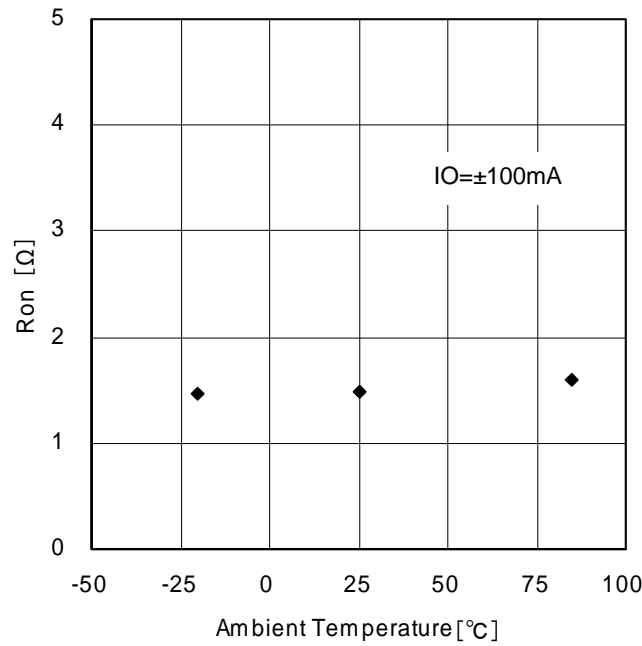


Figure 6. Output ON-Resistance
Temperature Dependency
(Voltage driver block)

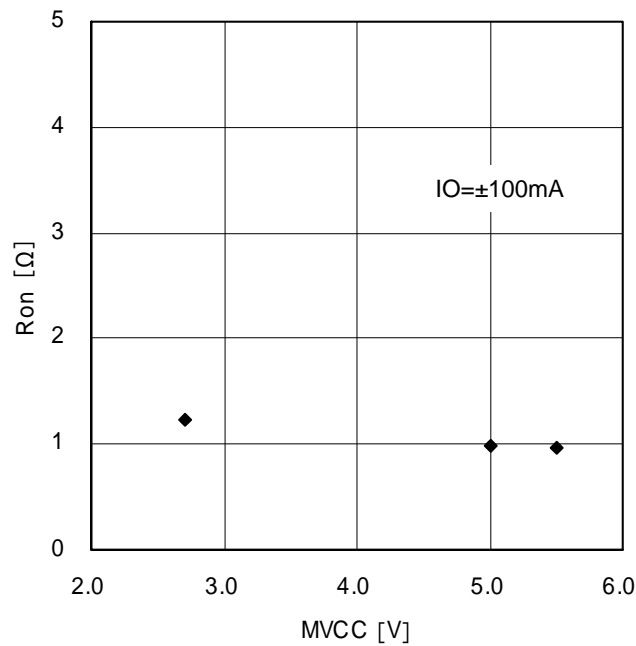


Figure 7. Output ON-Resistance
MVCC Dependency
(Current driver block)

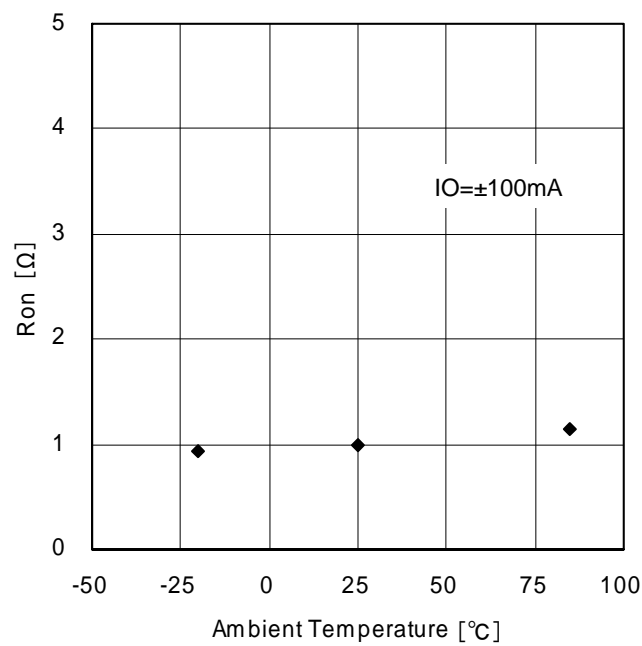


Figure 8. Output ON-Resistance
Temperature Dependency
(Current driver block)

● Typical Performance Curves

(Unless otherwise specified, $T_a=25^{\circ}\text{C}$, $\text{DVDD}=3.0\text{V}$, $\text{MVCC}=5.0\text{V}$, $\text{DVSS}=\text{MGND}=0.0\text{V}$)

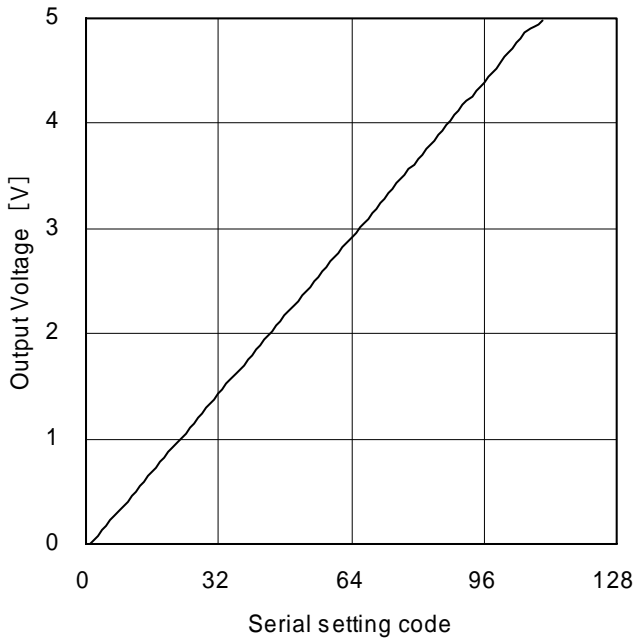


Figure 9. Average Voltage Accuracy
between different output pins
(Voltage driver block)

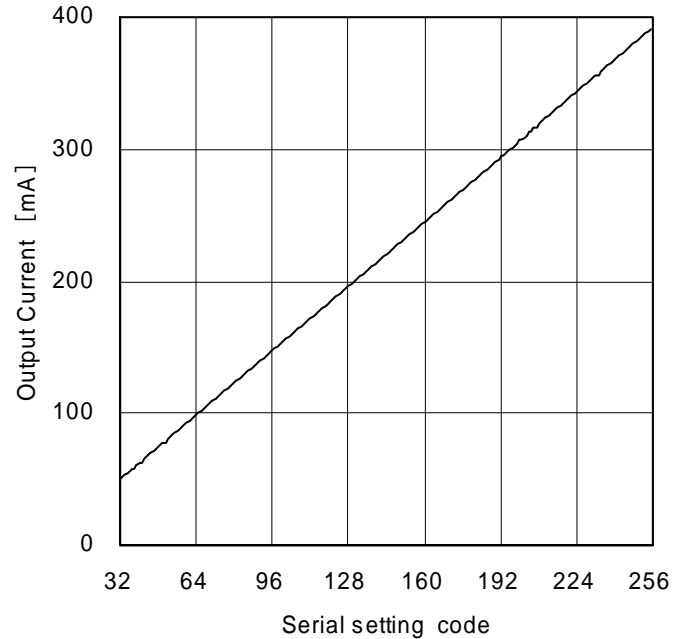


Figure 10. Output Current
(Current driver block, $\text{RRNF} = 1.0\Omega$, $\text{RL} = 5.0\Omega$)

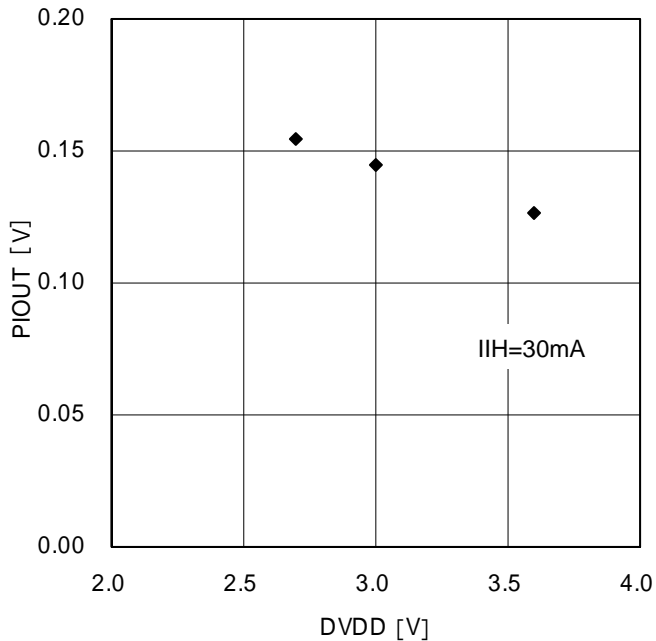


Figure 11. Output Voltage
DVDD Dependency
(PI driving circuit)

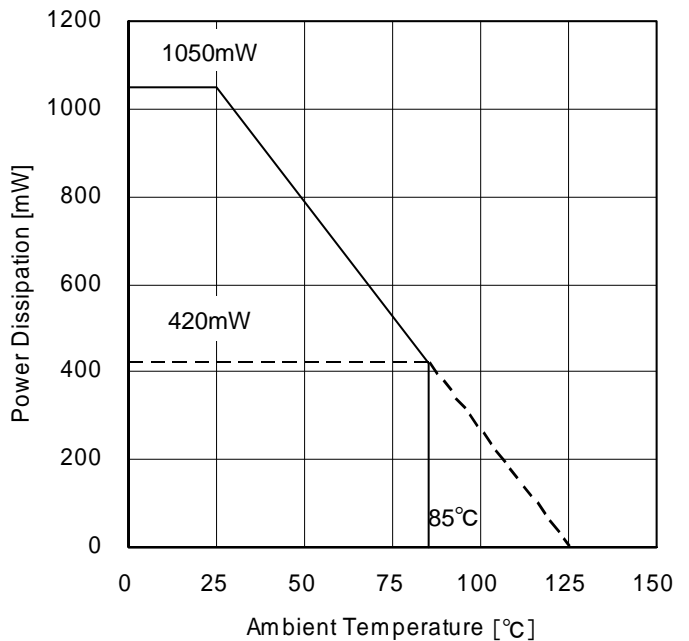
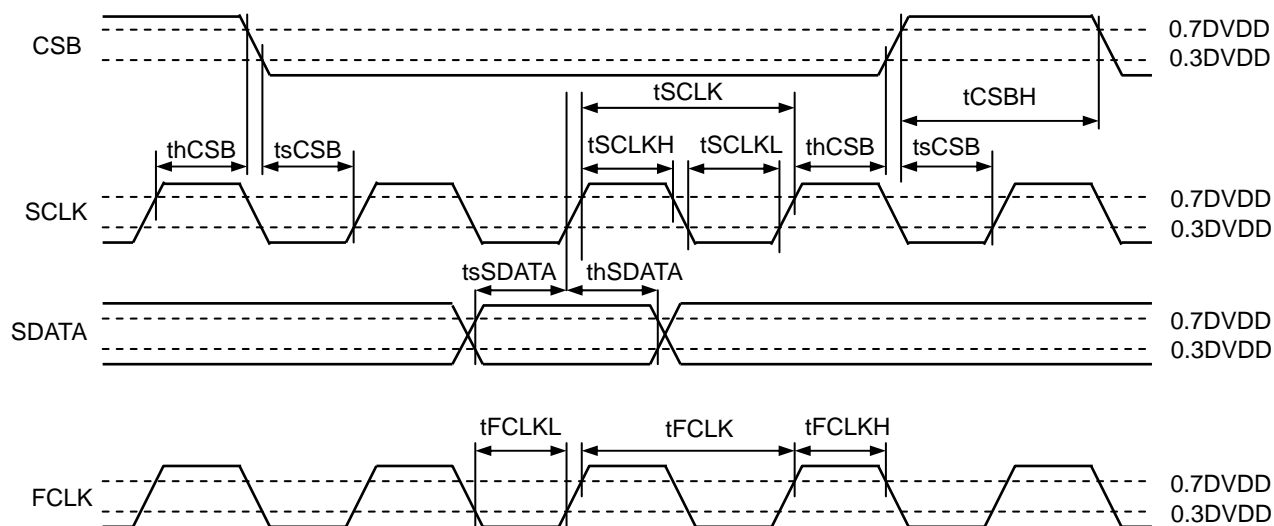


Figure 12. Power Dissipation Curve

●Timing Chart

(Unless otherwise specified, $T_a=25^{\circ}\text{C}$, $\text{DVDD}=3.0\text{V}$)

| Parameter | Symbol | Specification |
|-------------------------|---------|--------------------|
| SCLK input cycle | tSCLK | More than 100 nsec |
| SCLK L-level input time | tSCLKL | More than 50 nsec |
| SCLK H-level input time | tSCLKH | More than 50 nsec |
| SDATA setup time | tsSDATA | More than 50 nsec |
| SDATA hold time | thSDATA | More than 50 nsec |
| CSB H-level input time | tCSBH | More than 380 nsec |
| CSB setup time | tsCSB | More than 50 nsec |
| CSB hold time | thCSB | More than 50 nsec |
| FCLK input cycle | tFCLK | More than 36 nsec |
| FCLK L-level input time | tFCLKL | More than 18 nsec |
| FCLK H-level input time | tFCLKH | More than 18 nsec |

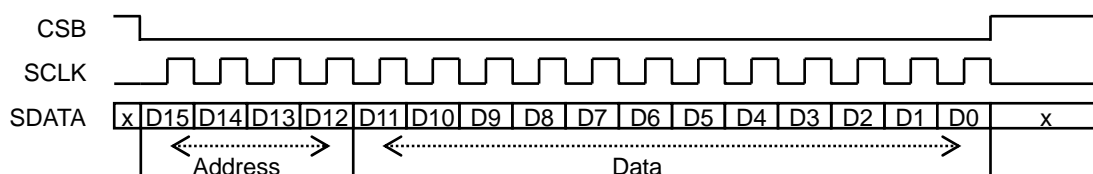


(note1) FCLK is asynchronous with SCLK.
 (note2) Duty of FCLK, SCLK are free.

●Serial interface

Control commands are framed by a 16-bit serial input (MSB first) and are sent through CSB, SCLK, and SDATA pins.

The 4 higher-order bits specify addresses, while the remaining 12 bits specify data. Data of every bit is sent through SDATA pin, which is retrieved during the rising edge of SCLK. Data becomes valid when CSB is Low and is registered during the rising edge of CSB.



<Register map>

| Address[3:0] | | | | Data[11:0] | | | | | | | | | | | |
|----------------------------------|----|----|----|--------------------|------|----------------------------------|------------------|---------------|---------------------------------|--------------------|--------|------------------|------------------|------------------|---------|
| 15 | 14 | 13 | 12 | 11 | 10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | 0 | 0 | 0 | A_Mode[1:0] | | A_SEL[2:0] | | | A_different_output_voltage[6:0] | | | | | | |
| 0 | 0 | 0 | 1 | 0 | 0 | 0 | 0 | A_Cycle[5:0] | | | | | | 0 | 0 |
| | | | | 0 | 0 | 1 | 0 | A_Cycle[13:6] | | | | | | | |
| | | | | 0 | 1 | 0 | 0 | 0 | 0 | 0 | 0 | A_Start_POS[3:0] | | | |
| | | | | 0 | 1 | 1 | 0 | A_BEXC | 0 | 0 | A_BSL | A_AEXC | 0 | 0 | A_AS |
| | | | | 1 | 1 | 1 | 0 | 0 | 0 | A_POS[1:0] | | 0 | A_UPDW_Stop | A_PS | A_Stop |
| 0 | 0 | 1 | 0 | A_EN | A_RT | A_Pulse[9:0] / A_UPDW_Cycle[9:0] | | | | | | | | | |
| 0 | 1 | 0 | 0 | B_Mode[1:0] | | B_SEL[2:0] | | | B_different_output_voltage[6:0] | | | | | | |
| 0 | 1 | 0 | 1 | 0 | 0 | 0 | 0 | B_Cycle[5:0] | | | | | | 0 | 0 |
| | | | | 0 | 0 | 1 | 0 | B_Cycle[13:6] | | | | | | | |
| | | | | 0 | 1 | 0 | 0 | 0 | 0 | 0 | 0 | B_Start_POS[3:0] | | | |
| | | | | 0 | 1 | 1 | 0 | B_BEXC | 0 | 0 | B_BSL | B_AEXC | 0 | 0 | B_AS |
| | | | | 1 | 0 | 0 | 0 | 0 | 0 | 3_CHOP[1:0] | | 0 | 0 | 4_CHOP[1:0] | |
| | | | | 1 | 0 | 1 | 3_State_CTL[1:0] | | 3_PWM_Duty[6:0] | | | | | | |
| | | | | 1 | 1 | 0 | 4_State_CTL[1:0] | | 4_PWM_Duty[6:0] | | | | | | |
| | | | | 1 | 1 | 1 | 0 | 0 | 0 | B_POS[1:0] | | 0 | B_UPDW_Stop | B_PS | B_Stop |
| 0 | 1 | 1 | 0 | B_EN | B_RT | B_Pulse[9:0] / B_UPDW_Cycle[9:0] | | | | | | | | | |
| 1 | 0 | 1 | 1 | 0 | 0 | 0 | 0 | B_ANSEL | A_ANSEL | Edge | 0 | 0 | 0 | B_CTL | A_CTL |
| | | | | 0 | 0 | 1 | 0 | 0 | 0 | 0 | 0 | 0 | EXT_CTL[1:0] | | |
| 1 | 1 | 0 | 0 | 0 | 0 | Chopping[1:0] | | CacheM | 0 | 5_Mode | CLK_EN | CLK_DIV[3:0] | | | |
| 1 | 1 | 0 | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | PI_CTL2 | PI_CTL1 |
| | | | | 0 | 0 | 1 | 0 | DET_SEL | 0 | SPEN[1:0] | | 0 | 0 | 0 | 0 |
| | | | | 0 | 1 | 1 | 0 | TARSP[7:0] | | | | | | | |
| | | | | 0 | 1 | 1 | 1 | 0 | PSP[2:0] | | | 0 | ISP[2:0] | | |
| | | | | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | SPC_Limit[3:0] | | | |
| 1 | 1 | 1 | 0 | 0 | 0 | 0 | 0 | 5_IOUT[7:0] | | | | | | | |
| | | | | 0 | 0 | 1 | 0 | 0 | 5_PWM_Duty[6:0] | | | | | | |
| | | | | 0 | 1 | 0 | 0 | 0 | 0 | 5_CHOP[1:0] | | 0 | 0 | 5_State_CTL[1:0] | |
| | | | | 0 | 1 | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 6_State_CTL[2:0] | | |
| | | | | 1 | 0 | 0 | 0 | 6_IOUT[7:0] | | | | | | | |
| | | | | 1 | 0 | 1 | 0 | 0 | 0 | Waveform_Vthh[5:0] | | | | | |
| | | | | 1 | 0 | 1 | 1 | 0 | 0 | Waveform_Vthl[5:0] | | | | | |
| | | | | 1 | 1 | 0 | 0 | 0 | 0 | 0 | STB | 0 | 0 | STM_RS | CMD_RS |
| Addresses other than those above | | | | Setting prohibited | | | | | | | | | | | |

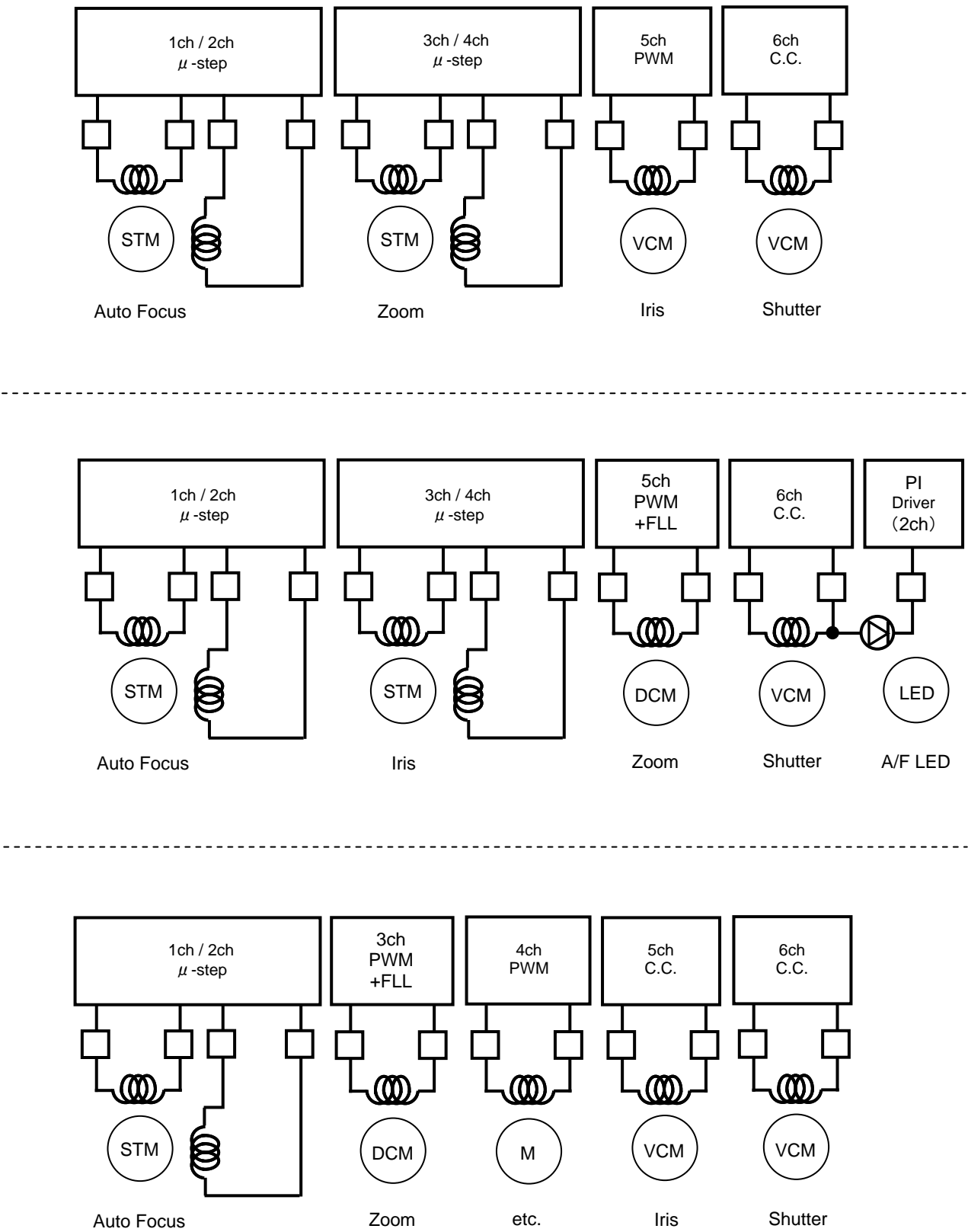
(Note 1) The notations A and B in the register map correspond to Ach and Bch respectively. Ach is defined as 1ch and 2ch driver, Bch as 3ch and 4ch driver.

(Note 2) After reset (Power ON reset), the initial condition is saved in all registers.

(Note 3) For Mode, different output voltage, Cycle, EN, and RT registers, data that are written before the access to the Pulse register becomes valid and determines the rising edge of CSB after the access to the Pulse register.

(The Mode, different output voltage, Cycle, EN, RT, and Pulse registers contain Cache registers. Any registers other than those do not contain Cache registers.)

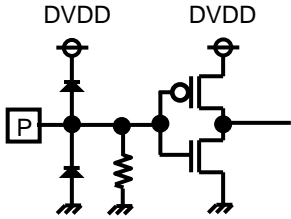
●Application Example



●I/O Equivalence Circuit

| Pin | Equivalent Circuit Diagram | Pin | Equivalent Circuit Diagram |
|------------------------------------|----------------------------|----------------------------------|----------------------------|
| FCLK CSB SCLK SDATA IN | | SI | |
| STATE11 STATE21 | | STATE12 STATE22 SO | |
| PIOUT1 | | PIOUT2 | |
| OUT1A OUT1B OUT2A OUT2B | | OUT3A OUT3B OUT4A OUT4B | |
| OUT5A OUT5B | | OUT6A OUT6B | |

●I/O Equivalence Circuit

| Pin | Equivalent Circuit Diagram |
|-----------------|---|
| TEST (note1) |  |

(note1) Short TEST pin to DVSS.

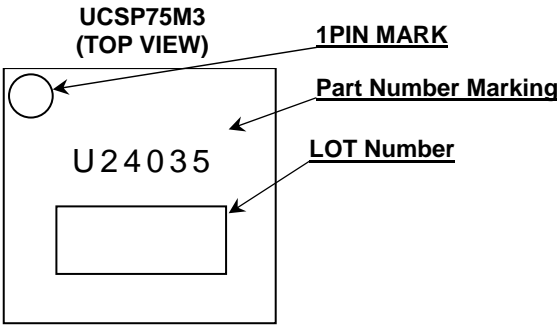
●Operational Notes

- 1) Absolute maximum ratings
If applied voltage, operating temperature range, or other absolute maximum ratings are exceeded, the LSI may be damaged. Do not apply voltages or temperatures that exceed the absolute maximum ratings. If you expect that any voltage or temperature could be exceeding the absolute maximum ratings, take physical safety measures such as fuses to prevent any conditions exceeding the absolute maximum ratings from being applied to the LSI.
- 2) GND potential
The voltage of the ground pin must be the lowest voltage of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.
- 3) Thermal design
Use a thermal design that allows for a sufficient margin by taking into account the permissible power dissipation (PD) in actual operating conditions.
- 4) Short circuit between pins and malfunctions
Ensure that when mounting the IC on the PCB the direction and position are correct. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.
- 5) Operation in strong magnetic field
Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.
- 6) Power ON sequence
To turn ON the DVDD, be sure to reset at CMD_RS register.
- 7) Thermal shutdown
The IC incorporates a built-in thermal shutdown circuit, which is designed to turn off the IC when the internal temperature of the IC reaches a specified value. It is not designed to protect the IC from damage or guarantee its operation. Do not continue to operate the IC after this function is activated. Do not use the IC in conditions where this function will always be activated.
- 8) PI drive circuit
The output voltage of PIOUT1 should not exceed the voltage of the power supply voltage DVDD.
The output voltage of PIOUT2 should not exceed the voltage of the power supply voltage VDDAMP.

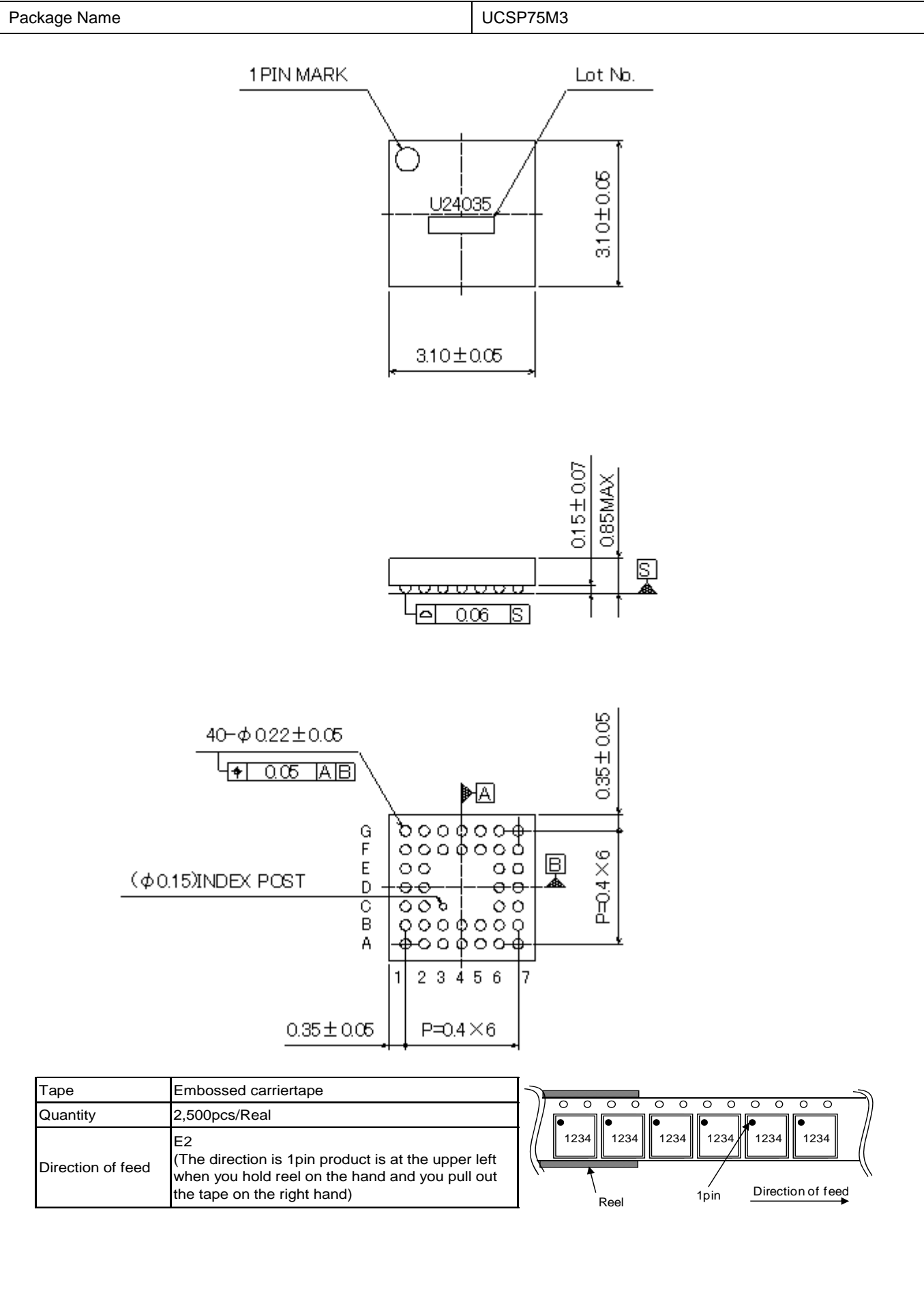
●Ordering Information

| | | | | | | | | | | | | |
|-------------------|--|--|--|--|--|--|--|--|--|---------------------------|-----|---|
| B U 2 4 0 3 5 G W | | | | | | | | | | - | E 2 | |
| Part Number | | | | | | | | | | Package GW UCSP75M3 | : | Packaging and forming specification E2: Embossed tape and reel |

●Marking Diagram



●Physical Dimension Tape and Reel Information



●Revision History

| Date | Revision | Changes |
|-------------|----------|---|
| 26.Sep.2012 | 001 | New Release |
| 18.Apr.2013 | 002 | Update some English words, sentences, descriptions, grammar and formatting. |

Notice

Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

| JAPAN | USA | EU | CHINA |
|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV | | CLASS III | |

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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 - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
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- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
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- Защиту от снятия компонента с производства.
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